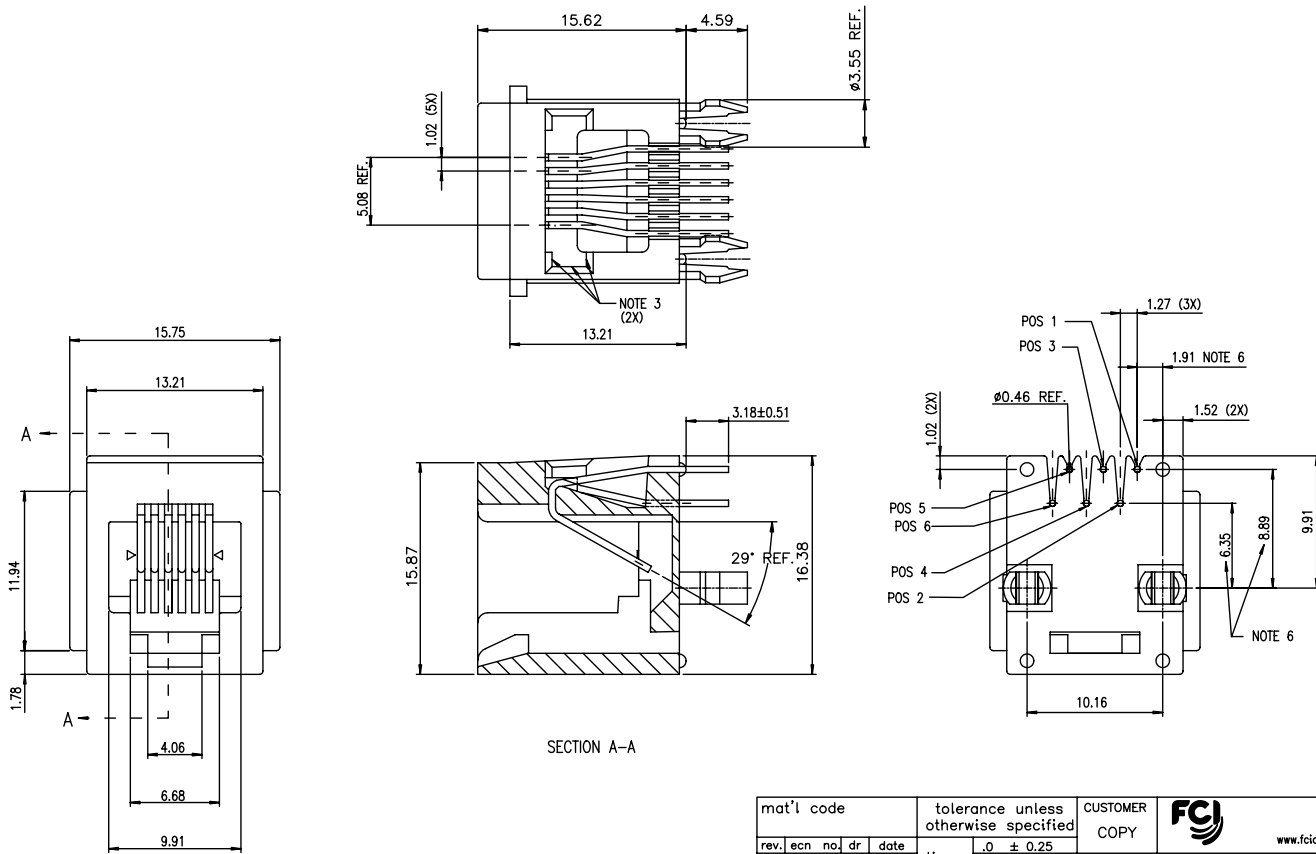


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PRODUCT NO.  
SEE TABLE



mat'l code		tolerance unless otherwise specified		CUSTOMER		FCI	
rev.	ecn no.	dr	date	linear	.0 ± 0.25	COPY	www.fciconnect.com
H	N08-0170	SH	10/08/08		.00 ± 0.13	projection	title
B	T90021	M	01/19/99		.000 ± 0.05		6 POS VERT. SPECIAL PEG
C	N10059	WL	05/22/01	angles	± 2°		P.C.B. III MOD JACK ASSY
D	N04-0023	DM	06/07/04	dr	C L FENG D2/21/97	unit	product family MOD JACK
E	N04-0125	YS	12/08/04	enr	TONY CHIEN D2/21/97	mm/inch	code
F	N05-0099	YS	04/01/05	chr	TONY CHIEN D2/21/97	scale	TWN
G	N08-0097	SH	08/24/08	appd	JENN TSAO D2/21/97	size	dwg no.
sheet	revisor	C	C			A3	61837
index	sheet	1	2				1 OF 2

PDM: Rev:H STATUS:Released Printed: Aug 01, 2010

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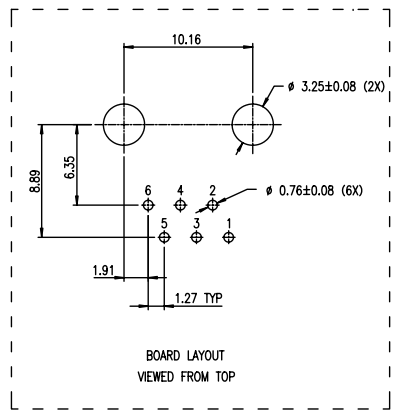
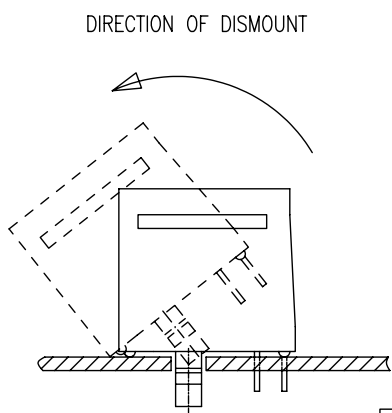
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PRODUCT NO.	POSITIONS LOADED	HOUSING P/N	HSG COLOR
61837-X661			
-X661LF	ALL	61836-001	BLACK
-X661HLF		61836-011	BLACK
-X641	2,3,4,5	61836-001	BLACK
-X641LF		61836-011	BLACK
-X621	3,4	61836-001	BLACK
-X621LF		61836-011	BLACK
-X662	ALL	61836-002	GREY
-X662LF		61836-012	GREY
-X642	2,3,4,5	61836-002	GREY
-X642LF		61836-012	GREY
-X622	3,4	61836-002	GREY
-X622LF		61836-012	GREY
-X612	1,6	61836-002	GREY
-X612LF		61836-012	GREY

- NOTES :
- P/N WITH DASH X6XX -NORMAL WAVE SOLDERING APPLICATION.
  - PACKAGING SPEC. GES-14-351 (USING TRAY).
  - SCRATCH MARKS ACCEPTABLE ON THESE SURFACES.
  - JACK IS FOR 1.57/.062 THICK PCB.
  - SHOULD THE JACK NEED TO BE DISMOUNTED FROM THE PCB. PLS REMOVE JACK AS PER RECOMMENDED METHOD HEREIN. (DETAIL A) NIPPING THE LEGS OF THE PEG TOGETHER IS DISALLOWED, OTHERWISE LEG BREAKAGE MAY OCCUR.
  - THESE DIMENSIONS ARE MEASURED FROM THE TOP OF THE PEG.
  - THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
  - IF LF P/N PACKSGING MEETS GS-14-920 SPECIFICATION
  - THE HOUSING WILL WITHSTAND EXPOSURE TO 260° PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.57mm MINIMUM THICK CIRCUIT BOARD
  - EQUIVALENT THICKNESS Au AND GXT PLATING HAVE SAME FUNCTION AND THEY ARE ALTERNATIVE BY THE CUSTOEMR .

LEAD FREE PRODUCT NO.  
MEETS PIP PROCESS PRODUCT NO.

PLATING CODE X	PLATING
0	30 μ" / .76 μM G.X.T.
1	15 μ" / .38 μM GOLD
3	30 μ" / .76 μM GOLD
5	50 μ" / 1.27 μM GOLD



JACK DISMOUNT METHOD  
DETAIL A  
NOTE 5

mat'l code		tolerance unless otherwise specified		CUSTOMER COPY		FCJ www.fciconnect.com	
rev.	ecn no.	dr	date	linear	.0 ± 0.25	projection	title
H					.00 ± 0.13	⊕	6 POS VERT. SPECIAL PEG
				angles	.000 ± 0.05		P.C.B. III MOD JACK ASSY
					± 2°		
				dr	C L FENG D2/20/97	unit	product family MOD JACK
				enrg	TONY CHIEN D2/20/97	mm/inch	code
				chr	TONY CHIEN D2/20/97	scale	size dwg no.
				appd	JENN TSAO D2/20/97		A3 61837
sheet	revisor						code
index	sheet						TWN
							sheet
							2 OF